



line 9, delete

"BACKGROUND OF THE INVENTION" and insert therefor

- - Description of the Background - -.

Page 3, line 31, delete "EMBQDIMENT" and insert therefor - -EMBODIMENTS- -.

IN THE CLAIMS

Claim 1, line 1, delete "Substrate" and insert therefor - - A substrate - -.

Claims 2-13, line, delete "Substrate" and insert therefor - - The substrate - -.

Claim 14, line 1, delete "Security" and insert therefor - - A security - -.

Claim 15, line 1, delete "Security" and insert therefor - - A security - -.

Claim 16 line 1, delete "Security" and insert therefor - - A security - -.

Claim 17, line 1, delete "Optically" and insert therefor - - An optically - .

Please add the following new Claims:

- -18. The substrate according to Claim 1, which further comprises polyimide having polyaniline blocks thereon underneath said semiconductive organic polymer.
- 19. The substrate according to Claim 1, which further comprises an insulating layer on said semiconductive organic polymer.
 - 20. The substrate according to Claim 1, having an uppermost layer of polyaniline.
- 21. The substrate according to Claim 1, wherein the paper has a thickness up to $100\mu m$.
 - 22. The security paper according to Claim 14, which is a banknote.
 - 23. The security document according to Claim 15, which is a passport.
 - 24. The security document according to Claim 15, which is an identity card.
 - 25. The security document according to Claim 15, which is a security.--